

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5142325

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
XINHONG CHENG	07/25/2018
XINCHANG LI	07/25/2018
ZHONGHAO WU	07/25/2018
DAWEI XU	07/25/2018
YUEHUI YU	07/25/2018
RECEIVING PARTY DATA	
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Postal Code:	200050
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16085423
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DATE SIGNED:	09/14/2018
Total Attachments: 1	
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ASSIGNMENT

GUH-377US

WHEREAS, I/WE:

CHENG, Xinhong; LI, Xinchang; WU, Zhonghao; XU, Dawei; YU, Yuehui, residing in No.865, Changning Road, Changning District, Shanghai-200050, China

have invented certain new and useful improvements in the following:

BATTERY MANAGEMENT CHIP CIRCUIT ON THE BASIS OF SILICON ON INSULATOR (SOI) PROCESS

for which a United States patent application therefor has been executed on 7/25/2018, U.S. Patent Application No.: 16085423

WHEREAS,

SHANGHAI INSTITUTE OF MICROSYSTEM AND INFORMATION TECHNOLOGY, CHINESE ACADEMY OF SCIENCES

(hereinafter referred to as the Assignee), residing at No.865, Changning Road, Changning District, Shanghai-200050, China desires to acquire the entire right, title and interest in said application and invention, and to any United States and foreign patents to be obtained therefor.

NOW THEREFORE, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to Assignee, its successors and assigns, the entire right, title and interest in said application and inventions therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said application, I/we hereby agree that Assignee may apply for foreign Letters Patent on said inventions, and I/we hereby agree to timely execute all papers necessary in connection with said United States and foreign Letters Patent applications when called upon to do so by Assignee.

I/we hereby covenant that I/we have the full and lawful right to convey the entire right, title, and interest herein assigned, and that I/we have not entered and will not enter into any agreement in conflict herewith.

I/we hereby request the Commissioner for Patents to issue any Letters Patent granted upon the inventions set forth in said application to Assignee, its successors and assigns.

ASSIGNOR SIGNATURE(S)

Xinhong Cheng
CHENG, Xinhong

2018.07.25
Date

Xinchang Li
LI, Xinchang

2018.07.25
Date

Wu Zhonghao
WU, Zhonghao

2018.07.25
Date

Xu Dawei
XU, Dawei

2018.7.25
Date

[Signature]
YU, Yuehui

2018.07.25
Date